	Туре	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	13	koh near kwan.in.	(H: P() •	2004/12/0 7 18:24
2	BRS	L2	0	(oxynitride-nitride- oxynitride) near15 (polysilicon)	US- PGPUB ; USPAT	2004/12/0 7 18:25
3	BRS	L3	548	(oxide-nitride-oxide) near15 (polysilicon)	US- PGPUB ; USPAT	2004/12/0 7 18:27

	Туре	L #	Hits	Search Text	DBs	Time Stamp
4	BRS	L4	2015	((oxide-nitride-oxide) or (ono)) near15 (polysilicon)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2004/12/0 7 18:27
5	BRS	L5	171	((oxide-nitride-oxide) or (ono)) near15 (polysilicon) near25 (tunnel)	US- PGPUB; USPAT; EPO; JPO; DERWE NT; IBM_T DB	2004/12/0 7 18:28
6	BRS	L6	281	((oxide-nitride-oxide) or (ono)) near15 (polysilicon) near25 (tunnel or oxide) near25 (wafer or substrate)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2004/12/0 7 18:28

	Туре	L	#	Hits	Search Text	DBs	Time Stamp
7	BRS	L7		2		US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2004/12/0 7 18:29
8	BRS	L8		8	<pre>((oxide-nitride-oxide) or (ono)) near15 (polysilicon) near25 (tunnel or oxide) near25 (wafer or substrate) near25 (sti or trench near3 isolation)</pre>	US- PGPUB; USPAT; EPO; JPO; DERWE NT; IBM_T DB	2004/12/0 7 18:45
9	BRS	L9		281	((oxide-nitride-oxide) or (ono)) near15 (polysilicon) near25 (tunnel or oxide) near25 (wafer or substrate)	US- PGPUB; USPAT; EPO; JPO; DERWE NT; IBM_T DB	2004/12/0 7 18:45

	Туре	L	#	Hits	Search Text	DBs	Time Stamp
10	BRS	L10			((oxide-nitride-oxide) or (ono)) near15 (polysilicon or poly- silicon) near25 (tunnel or oxide)	US- PGPUB; USPAT; EPO; JPO; DERWE NT; IBM_T DB	2004/12/0 7 18:57
11	BRS	L11		l	((oxide-nitride-oxide) or (ono)) near15 (polysilicon or poly- silicon or poly near silicon) near25 (tunnel or oxide) near25 (wafer or substrate)	US- PGPUB; USPAT; EPO; JPO; DERWE NT; IBM_T DB	2004/12/0 7 18:57
12	BRS	L12		286	((oxide-nitride-oxide) or (ono)) near15 ((polysilicon or poly- silicon) or (poly near silicon)) near25 (tunnel or oxide) near25 (wafer or substrate)	US- PGPUB; USPAT; EPO; JPO; DERWE NT; IBM_T DB	2004/12/0 7 18:57

	Туре	L #	Hits	Search Text	DBs	Time Stamp
13	BRS	L13	15	<pre>((oxide-nitride-oxide) or (ono)) near15 ((polysilicon or poly- silicon) or (poly near silicon)) near25 (tunnel or oxide) near25 (wafer or substrate) near25</pre>	; USPAT	2004/12/0 7 18:57

	U	1	Do	cument ID	Title	Current OR
1			US B1		Method for fabricating nitride read only memory	438/275
2			US B1	6436778	Re-oxidation approach to improve peripheral gate oxide integrity in a tunnel nitride oxidation process	438/305
3			US B1	6376877	Double self-aligning shallow trench isolation semiconductor and manufacturing method therefor	257/317
4			TW		Manufacture of trench- type flash memory increases capacitor coupling ratio to improve device performance	
5			US	6121148 A	Formation of a polysilicon-contacted trench isolation structure by etching an exposed portion of the substrate's surface, etching the trench lining silicon nitride, and depositing another polysilicon layer	·

	บ	1	Document	ID	Title	Current (OR
6			TW 388131	•	Improving the coupling ratio of wordline of stacked gate flash memory element to floating gate comprises sequentially forming a first oxide layer, a first nitride layer on a semiconductor wafer; defining a trench isolat		
7			US 585188	1 A	Multi-level logic flash memory cell, EEPROM - comprises a poly stacked gate transistor in series with a MONOS transistor		
8			US 550616	0 A	Alternate metal ground EPROM device fabrication with scaling to 0.6 micron - allowing formation of 64 mega bit EPROM arrays		